

L Number	Hits	Search Text	DB	Time stamp
2	0	((29/832).CCLS.) and (sensor\$ near3 optical) and(anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 11:00
3	0	((29/832).CCLS.) and (sensor\$ near3 optical) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:50
4	0	((29/832).CCLS.) and (sensor\$ near3 assembly) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:50
5	3061	((29/739) or (29/740)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:50
6	0	((29/739) or (29/740)).CCLS.) and (sensor\$ near3 assembly) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:50
7	2	(("6156978") or ("5750202")).PN.	USPAT	2004/04/27 10:51
	5	((438/118).CCLS.) and (sensor\$ near3 assembly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:51
8	217	(156/102).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:51
9	475	(156/298).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:51
10	1177	(156/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:52
11	354	(156/358).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:52
12	210	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:52
13	271	((156/367) or (156/368)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:52

14	737	((156/378) or (156/379)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:52
15	619	(156/299).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:52
16	2162	(29/832).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:53
17	7	((29/832).CCLS.) and (sensor\$ near3 optical) and (solder) and (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:53
18	46	((29/832).CCLS.) and (sensor\$) and (solder) and (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:53
19	7	((29/739) or (29/740)).CCLS.) and (sensor\$) and (anisotropic\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:53
20	1163	(438/118).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:54
21	124	(156/\$.ccls.) and (indium or germanium) and (anisotropic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:54
22	3	(156/\$.ccls.) and (germanium near3 solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:54
23	23	(156/\$.ccls.) and (compression\$) and (die near2 bond\$) and (damage)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:54
24	115	(thermoset\$ same thermoplast\$) and (sensor\$ near3 assembly) and (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:54
25	3	(156/\$.ccls.) and (sensor\$3) and (anisotropic\$3) and ((thermoset\$4 or cure or curable) same (transparent))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/27 10:54